

IN THE CLAIMS

Please amend the claims as follows:

1. – 22. (Canceled)

23. (Previously Presented) A method for singulating dies from a wafer comprising:
laser scribing a first continuous line;
laser scribing a second continuous line spaced apart from the first continuous line;
laser scribing a third continuous line, the third continuous line positioned between the first continuous line and the second continuous line; and
passing a saw through the area of the first continuous line, the second continuous line and the third continuous line to cut the wafer.

24. (Currently Amended) The method for singulating dies from a wafer of claim [[24]] 23 wherein the first continuous line, the second continuous line and the third continuous line overlap.

25. (Currently Amended) The method for singulating dies from a wafer of claim [[24]] 23 wherein the third continuous line overlaps the second continuous line and the third continuous line.

26. (Currently Amended) The method for singulating dies from a wafer of claim [[24]] 23 wherein the first continuous line, the second continuous line and the third continuous line are formed from overlapping pulses from a laser.

27. (Currently Amended) The method for singulating dies from a wafer of claim [[24]] 23 wherein the first continuous line, the second continuous line and the third continuous line overlap are in an area having a width greater than the width of a kerf from a saw blade of the saw.

28. -38. (Canceled)